

Subject: Re: MICROCHIP WAFFLE MO852479 2ND OPT LOW YIELD
From: Emms <emmanuelle.orela@teamglac.com>
To: Angela Marquez <angela.marquez@teamglac.com>
Date: 2024-02-12 8:20 am



Hi Angela,

Details Attachments History Observer(s)

Review Cycle	User	Action	Disposition	Comments
1	SPS_SLD_ASSY	Submit Disposition	Release good, Scrap Rejects	[Acted by: James Mirana - A30118] Pls release remaining good to next process [C Supp_TeamPacific_Philippines_SLD Contact]
1	emmanuelle.orela@teamglac.com	Submitted	Waiting For Disposition	[Current Owner: SPS_SLD_ASSY]

On 12/02/2024 7:28 AM, Angela Marquez wrote:

Hello Ate Emms,

ate pa advisan din yung customer na if pati yung mga succeeding PT's from MO852480-90 is ipapa-apply na din yang low yield disposition. kasi for sure pati yung mga kasunod na PT's is lowyield din.

--
Thank you!
With Best Regards,



On 2024-02-08 3:40 pm, Emms wrote:

Hi Ate Girlie,

Please help to follow-up below SLD



Subcon Lot Disposition

Assembly: SLDO064365 | TEAM | 08 Feb 2024 | emmanuelle.orela@teamglac.com | MCHP Subcon Ops Review

Details Attachments History Observer(s) Disposition ID Recall Linked SLD

Issue Details

Location:	Reject Code (Level 1):	Reject Code (Level 2):
Team Pacific Corp. Philippines - TEAM	2nd OP Defects	2nd OP Defects
QA Criteria:	FEEDBACK	

regards,
emms

On 08/02/2024 3:34 PM, Marelene Caspe wrote:

Hi Ems,

Please see below lots low yield at 2nd optical inspection

Lot Details:

Customer: MICROCHIP
Package: WP_RF423 WAFFLE PACK
Die Lot No: S95967
MO No : **MO852479**
PT Qty: 1964
Actual Qty: 1570
Yield: 79%

--
Thank you!
With Best Regards,

LOW YIELD NOTIFICATIONLYN NO.: 24-02-1981YIELDING STATION : X9DATE : 12 FEB '24LOT DETAILSCUSTOMER : MICROSEMPACKAGE : NATIVE PACKDEVICE : RPA23PT No. : MD852479LOT No. : SAT007JOB/RO No. : PON080061519PO No. : PO104001501

For Second Optical Inspection Only:

Start Date : 06 FEB '24Wafer No. : 1-2Inspection Date : 07 FEB '24Problem Description: LOW YIELD DUE TOFABRICATION DEFECTS.

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	SZ	920	/			SCRAP			
2	PM	44	/						
3	MV	15	/						
4	100	4	/						
5	CHO	1	/						
6	CNO	1	/						
7		7	344						
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.).
- ✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1964	1570	79-9%
RETEST			
FINAL		NA	NA

Note: If not applicable please write NA on the space provided.

F. PIZARRA / 12 FEB 24 / F.P.
SE/TE / Date / SignatureFINAL LOT DISPOSITION: Move good parts to the next operation Scrap Others (please specify): _____A. Marquez / 1/2/24 / A. Marquez
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATIONLYN NO.: 24-02-1982YIELDING STATION : N/A
DATE : 12 FEB '24LOT DETAILS

CUSTOMER : MICROSEM
 PACKAGE : WAFER PACK
 DEVICE : RPU23
 PT No. : M0852486
 LOT No. : S 20967
 JOB/RO No. : P0008006519
 PO No. : P0104001521

For Second Optical Inspection Only:

Start Date	<u>06 FEB '24</u>
Wafer No.	<u>3-4</u>
Inspection Date	<u>08 FEB '24</u>

Problem Description: LOW YIELD DUE TO FABRICATION DEFECTS

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	SZ	900	/			SCRAP			
2	PIN	28	/						
3	MV	25	/						
4	VTROP	4	/						
5	CHD	2	/						
6									
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.),
✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1004	1001	81.5%
RETEST			
FINAL	NA	NA	

Note: If not applicable please write NA on the space provided.

F-PIARRA / 12 FEB '24 / *Tiji*
SE/TE / Date / Signature

FINAL LOT DISPOSITION:

- Move good parts to the next operation
 Scrap
 Others (please specify): _____

A. Manjuri / 2/12/24 / *Manjuri*
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATION

LYN NO.: 24-02-1983

YIELDING STATION : X0
DATE : 10 FEB '24

LOT DETAILS

CUSTOMER : MICROSONIC
PACKAGE : NOVCO PACK
DEVICE : RF420
PT No. : M0850481
LOT No. : SAC967
JOB/RO No. : P0008000619
PO No. : P0104031561

For Second Optical Inspection Only:

Start Date	<u>06 FEB '24</u>
Wafer No.	<u>5-C</u>
Inspection Date	<u>08 FEB '24</u>

Problem Description: LOW YIELD DUE TO PARASITICATION DEFECTS.

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	SZ	300	/						
2	FM	30	/						
3	CHO	5	/			Scrap			
4	MW	15	/						
5	ND	2	/						
6	S00	3	/						
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.).
✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1004	1080	80.4%
RETEST			
FINAL	X0	X0	

Note: If not applicable please write NA on the space provided.

A. ABUOAH / 13 FEB '24 / A.
SE/TE / Date / Signature

FINAL LOT DISPOSITION:

- Move good parts to the next operation
 Scrap
 Others (please specify): _____

A. ABUOAH / 13 FEB '24 / A.
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATIONLYN NO.: 24-02-1985

YIELDING STATION

DATE

NO

10 FEB '24

LOT DETAILS

CUSTOMER

MICROCHIP

PACKAGE

NATTVO PACK

DEVICE

RF42B

PT No.

M0653482

LOT No.

S95707

JOB/RO No.

PONO80061519

PO No.

PO104001501

For Second Optical Inspection Only:

Start Date : 06 FEB '24

Wafer No. : 7-8

Inspection Date : 10 FEB '24

Problem Description: LOW YIELD DUE TO POLARIZATION DEFECTS.

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	RE	449	/						
2	FM	5	/			Scrap			
3	AN	10	/						
4	CHO	3	/						
5									
6									
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.).
- ✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1904	1525	77.6%
RETEST			
FINAL	NA	NA	

Note: If not applicable please write NA on the space provided.

FINAL LOT DISPOSITION:

Move good parts to the next operation



Scrap



Others (please specify): _____

A. ABUO A / 13 FEB '24 / Ani
SE/TE / Date / SignatureA. Marques / 13 FEB '24 / Marques
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATION

LYN NO.: 24-02-1984

YIELDING STATION
DATE

X10

10 FEB '24

LOT DETAILS

CUSTOMER

M10005001

PACKAGE

WAFER PACK

DEVICE

RF423

PT No.

10852483

LOT No.

JAS967

JOB/RO No.

PON080061519

PO No.

PO104001561

For Second Optical Inspection Only:

Start Date : 07 FEB '24

Wafer No. : 9-10

Inspection Date : 10 FEB '24

Problem Description: Low Yield due to fabrication defects.

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	SZ	982	/						
2	PN	20	/			Scrap			
3	MV	15	/						
4	CHO	9	/						
5			420						
6									
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.),
✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1064	1024	78.6%
RETEST			
FINAL	XNA	XNA	

Note: If not applicable please write NA on the space provided.

FINAL LOT DISPOSITION:

Move good parts to the next operation



Scrap



Others (please specify): _____

A. ABUOJA / 13 FEB '24 / *[Signature]*
SE/TE / Date / Signature

A. MARGO / 13 FEB '24 / *[Signature]*
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATIONLYN NO.: 24-02-1986

YIELDING STATION :

DATE :

NO

14 FEB 24

LOT DETAILS

CUSTOMER :

PACKAGE :

DEVICE :

PT No. :

LOT No. :

JOB/RO No. :

PO No. :

MICROSEM

NARROW PACK

RF439

M0852484

V27967

P010000061519

P0104031501

For Second Optical Inspection Only:

Start Date : 07 FEB 24

Wafer No. : 11-12

Inspection Date : 10 FEB 24

Problem Description: Low yield due to

Fabrication defects.

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	SZ	250+/-	/			7			
2	FM	25	/						
3	OTD	7	/			Scrap			
4	NN	15	/						
5	RCMR	50	/						
6									
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.),
 ✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1960	1610.06	80.79 82.12% FAB 24
RETEST			
FINAL	X-4	X-4	

FINAL LOT DISPOSITION:

Move good parts to the next operation



Scrap



Others (please specify): _____

Note: If not applicable please write NA on the space provided.

A. ABUDA / 15 FEB 24 / *[Signature]*
SE/TE / Date / SignatureA. Marquez / 2/14/24 / *[Signature]*
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATIONLYN NO.: 24-02-1987

YIELDING STATION

DATE

X9

14 FEB 24

LOT DETAILS

CUSTOMER

PACKAGE

DEVICE

PT No.

LOT No.

JOB/RO No.

PO No.

MICROSEM

WAFER PACK

RFU23

M0852485

S05767

P00080061519

P004001501

For Second Optical Inspection Only:

Start Date: 10 FEB '24

Wafer No.: 10-14

Inspection Date: 10 FEB 24

Problem Description: LOW YIELD DUE TO
FABRICATION DEFECTS.

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	SZ	305	/			7			
2	FAT	2	/						
3	MV	12	/						
4	OTD	3	/						
5	ODD	1	/						
6	PSMR	488	/						
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.).
- ✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1963	1052	53.7%
RETEST			
FINAL	X9	X69	

FINAL LOT DISPOSITION:

Move good parts to the next operation



Scrap



Others (please specify): _____

Note: If not applicable please write NA on the space provided.

A. ABUJA / 15 FEB '24 / 
SE/TE / Date / SignatureA. Marques / 14 FEB '24 / 
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATION

LYN NO.: 24-02-1988

YIELDING STATION : *NA*DATE : *14 FEB '24*LOT DETAILSCUSTOMER : *MICROFONI*PACKAGE : *WAFER PACK*DEVICE : *RPH29*PT No. : *MOES2487*LOT No. : *SAS167*JOB/RO No. : *PON080061519*PO No. : *PO104031501*

For Second Optical Inspection Only:

Start Date : *09 FEB '24*Wafer No. : *17-18*Inspection Date : *10 FEB '24*Problem Description: *LOW YIELD AND ID
PRODUCTION DEFECTS.*

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	SB	271	/						
2	TM	30	/			Scrap			
3	NA	17	/						
4	PSMR	2	/						
5									
6									
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.),
✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1904	1644	83.7%
RETEST			
FINAL	NA	X49	

Note: If not applicable please write NA on the space provided.

FINAL LOT DISPOSITION:

Move good parts to the next operation



Scrap



Others (please specify): _____

A. ABUDA / 15 FEB '24 / Ami
SE/TE / Date / Signature*A. Marquez / 02/14/24 / (Signature)*
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATION

LYN NO.: 24-02-1989

YIELDING STATION: NO
DATE: 14 FEB '24

LOT DETAILS

CUSTOMER: MICROSEM
PACKAGE: WAFER PACK
DEVICE: RPM20
PT No.: M0852488
LOT No.: SAC967
JOB/RO No.: P0080004519
PO No.: P010409161

For Second Optical Inspection Only:

Start Date: 09 FEB '24
Wafer No.: 19-30
Inspection Date: 10 FEB '24

Problem Description: LOW YIELD ON DUE TO
FABRICATION DEFECTS.

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	SZ	084	/						
2	FM	14	/						
3	CHD	0	/			Scrap			
4	CRO	3	/						
5	AN	14	/						
6	STOP	1	/						
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

- Notes:
• TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
• For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.),
✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1968	1549	78-79
RETEST			
FINAL	NA	NA	

Note: If not applicable please write NA on the space provided.

FINAL LOT DISPOSITION:

- Move good parts to the next operation
 Scrap
 Others (please specify): _____

A. ABUDA / 14 FEB '24 / Ani
SE/TE / Date / Signature

A. Marquez / 02/14/24 / Marquez
PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATION**LYN NO.: 24-02-1990**

YIELDING STATION : NA
DATE : 15 FEB '24

LOT DETAILS

CUSTOMER : MICROFOM 1
PACKAGE : NATIVE PACK
DEVICE : PNP23
PT No. : MOE52450
LOT No. : S95967
JOB/RO No. : PON0800 G1519
PO No. : P0104691501

For Second Optical Inspection Only:

Start Date : 10 FEB '24
Wafer No. : 21-22
Inspection Date : 10 FEB 24

Problem Description: LOW YIELD AND TO
PRODUCTION DEFECTS

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	5Z	321	/						
2	TM	14	/			Scrap			
3	MV	17	/						
4									
5									
6									
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.),
✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	1970	1618	82.1%
RETEST			
FINAL	X16	X16	

FINAL LOT DISPOSITION:

Move good parts to the next operation

Scrap

Others (please specify): _____

Note: If not applicable please write NA on the space provided.

A. ABALADA / 15 FEB '24 / Ani
 SE/TE / Date / Signature

A. Marquez / 2/15/24 / Marquez
 PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1

LOW YIELD NOTIFICATION

LYN NO.: 24-02-1991

YIELDING STATION

DATE : 15 FEB '24

LOT DETAILS

CUSTOMER : MICROSEM
 PACKAGE : Wafer Pack
 DEVICE : R7023
 PT No. : MOE834470
 LOT No. : S95907
 JOB/RO No. : PON080064519
 PO No. : P0104031561

For Second Optical Inspection Only:

Start Date : 10 FEB '24
 Wafer No. : 23 - 25
 Inspection Date : 14 FEB '24

Problem Description: LOW YIELD DUE TO
PEEL OFF CANTON DIRECT

ITEM No.	REJECT DESCRIPTION	TOTAL QTY	CLASSIFICATION			DISPOSITION	BILLING		JUSTIFICATION
			DIE RELATED	ASSY RELATED	OTHER		CHARGE TO CUSTOMER?	OTHERS?	
1	ST	672	/						
2	TM	15	/						
3	MV	25	/			Scrap			
4	CHO	2	/						
5	PSMR	6	/						
6									
7									
8									
9									
10									

(Dispositions: Scrap, retest, rework, send to customer w/ traceability, perform rel test, submit to FA lab, evaluate etc.)

Notes:

- TE / SE / Production to call attention of IE to provide cost study for retests and other activities that are beyond the standard process.
- For die sales and 2nd optical inspection yield / process, billing and justification portion may not be applicable (N.A.).
- ✓ QA supervisor/SH to inform the yield result to customer

TEST SUMMARY RESULTS			
	QTY IN	QTY OUT	YIELD
PRIME	2945	2185	74.1%
RETEST			
FINAL			

FINAL LOT DISPOSITION:



Move good parts to the next operation



Scrap



Others (please specify): _____

Note: If not applicable please write NA on the space provided.

A. ABUDIA / 15 FEB '24 / [Signature]
 SE/TE / Date / Signature

A. Maravalli / 15/02/24 / [Signature]
 PROD / Date / Signature

Note: For Assembly related rejects, Engg Dept. Head / SH is required to sign

TSOP-1028-F1